

How to Optimize and Control the Wire Bonding Process: Part I

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To help the reader follow the use of these tools/methods, step by step, we describe four possible situations in which a process needs to be developed, improved, or maintained. They are:

- New process development.

Improvement of a process running at low yield.

- Improvement and stabilization of a marginally acceptable process.

- Maintaining a process at an acceptable quality level.

As each situation is covered, we will discuss in detail the tools required, provide a brief statistical explanation, suggest further reading, and offer examples.

Developing a New Process

In this section we will describe the development of a new process. This method can be used for a new package type, new die, new wire bonder, etc.

Design of Experiments

Design of experiments (DOE) is a topic within the field of statistics [2]. It provides an efficient, structured approach to the problem of controlling a process with a large number of variables like wire bonding. By enabling one to efficiently explore the bonding process using many variables, designed experiments allow the engineer to determine which of the variables have significant effects on the process. Once they are identified through screening experiments, additional experiments provide mapping of the response surface and lead to efficient process optimization.

In contrast, a traditional method for conducting scientific experiments has been to hold everything constant while changing only one variable at a time. Data variation could then be attributed to the shift in that variable. This method poses two problems: it is very time consuming, and it does not measure the interaction between two variables since they must be varied simultaneously to see the effect. Often these factors in controlling a process.

The designed experiment described here for creating a new process includes five variables. It allows screening of all five variables with only 19 samples. Using the traditional one variable at a time approach would require over 80 samples! In addition, with DOE it is now possible to measure interaction effects which may prove to be very important.

ABSTRACT

To help process engineers improve, optimize, and control the wire bonding process, proven statistical analysis tools/techniques are provided to deal with four stages of a process. Part I covers developing a new process. Part II will discuss a process running at low yield, improving a marginally acceptable process, and maintaining process quality.

Wire bonding is an extremely high yield, high speed, automated manufacturing process. Modern wire bonders are capable of bonding 8 to 10 wires/sec and typical monthly throughput can exceed 500,000 devices. It's not unusual to see device yields approaching 99.99 percent with wire yields exceeding 99.999 percent. Total bonding defects are less than 100 parts per million (ppm), but real process optimization is required to achieve and maintain these yields. This article will discuss methods used to improve, optimize, and control the wire bonding process. These include design of experiments, response surface techniques, process capability studies, and control charts for high yield processes.

The use of designed experiments for screening wire bonding process variables and for optimizing the process will be described. They have been used extensively at K&S to establish new wire bonding processes and to design new, high reliability wire bonders such as the Model 1484XQ. They are easy to use and their data are easily analyzed. Process capability (and its relationship to design specifications) is also defined and discussed.

Many engineers have discovered the shortcomings of visual wire bond inspection. A logical alternative has been the use of statistical process control (SPC) control charts, but, unfortunately, conventional charts do not work well for very high yield processes. At defect levels below 1 percent, each defect generated results in an out-of-control signal. A new type of control chart has been proposed by T.N. Goh [1]. It is based on cumulative defects and it sets more appropriate levels for upper and lower control limits.

The combination of optimization methods mentioned above gives a reasonable, structured approach to controlling the wire bonding manufacturing process. With careful analysis of the observed defects and diligent attention to the largest defect generator, these methods will enable defects to be controlled and the process to be stabilized.

